



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PLCC2
- ▶ 3528+Lens Series
- ▶ Green (525nm)

NOG09S03



Release Date: 26 August 2020 Version: A1.1



APPLICATIONS:

- LED Display
- Indicator
- Traffic Display
- Decoration Lighting

3528+Lens Series

RoHS
Compliant



FEATURES:

- **Package:** PLCC2 White SMT Package with Lens
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 3.3V
- **Luminous Intensity (typ.):** 4200mcd@20mA
- **Colour:** Green
- **Wavelength:** 525nm
- **Viewing angle:** 30°
- **Materials:**
 - Die: InGaN
 - Resin: Epoxy (Water Clear)
 - L/F Finish: Ag Plated
- **Operating Temperature:** -40~+80°C
- **Storage Temperature:** -40~+85°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - Wavelength
- **Soldering methods:** Reflow soldering
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 12mm tape with 2000pcs/reel, ø330mm (13")

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Current @5V	I _R	10	μA
Power Dissipation	P _D	111	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

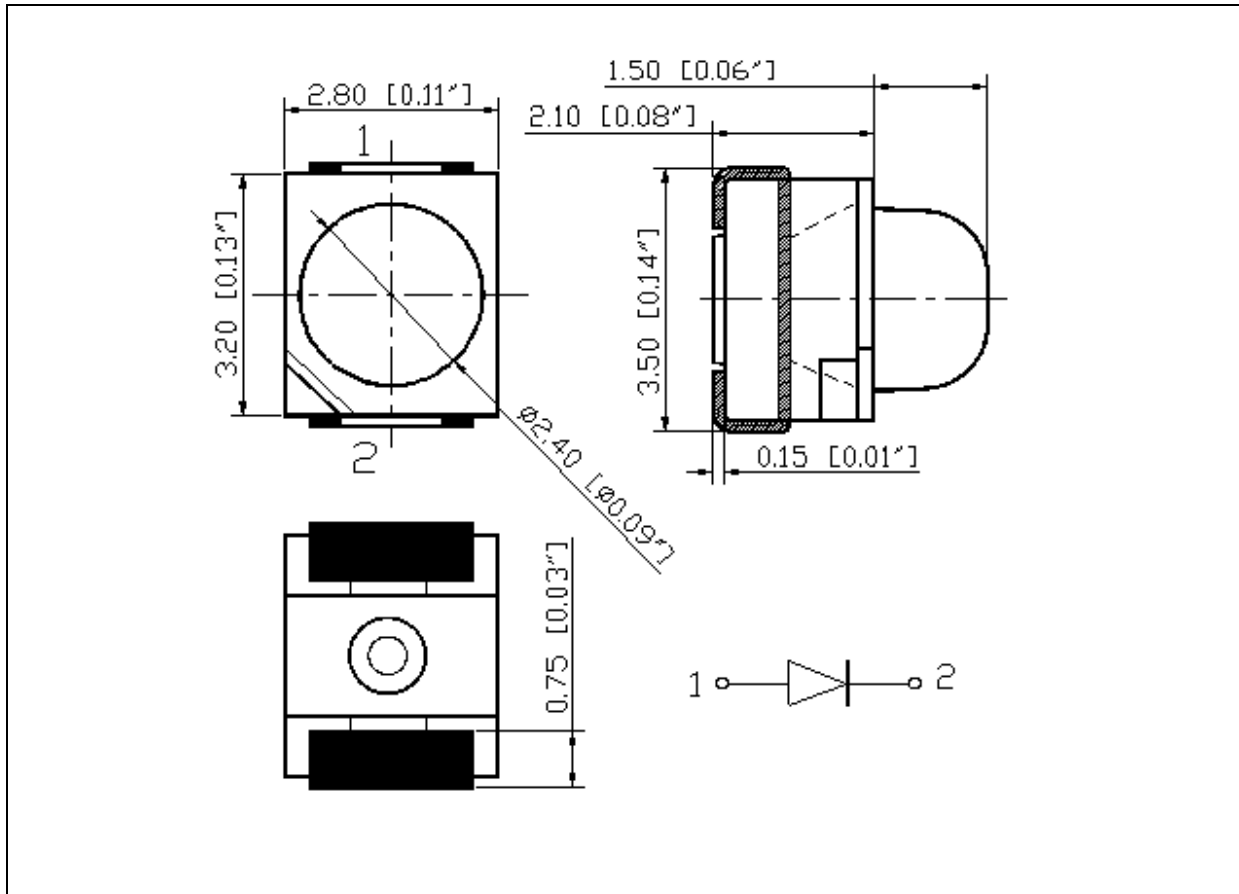
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	2.8	3.3	3.7	V	I _F =20mA
Luminous Intensity	I _v	2500	4200	6800	mcd	I _F =20mA
Dominant Wavelength	λ _D	520	525	530	nm	I _F =20mA
Peak Wavelength	λ _P	---	520	---	nm	I _F =20mA
Spectral Half Bandwidth	Δλ	---	35	---	nm	I _F =20mA
Viewing Angle	2θ _{1/2}	---	30	---	deg	I _F =20mA

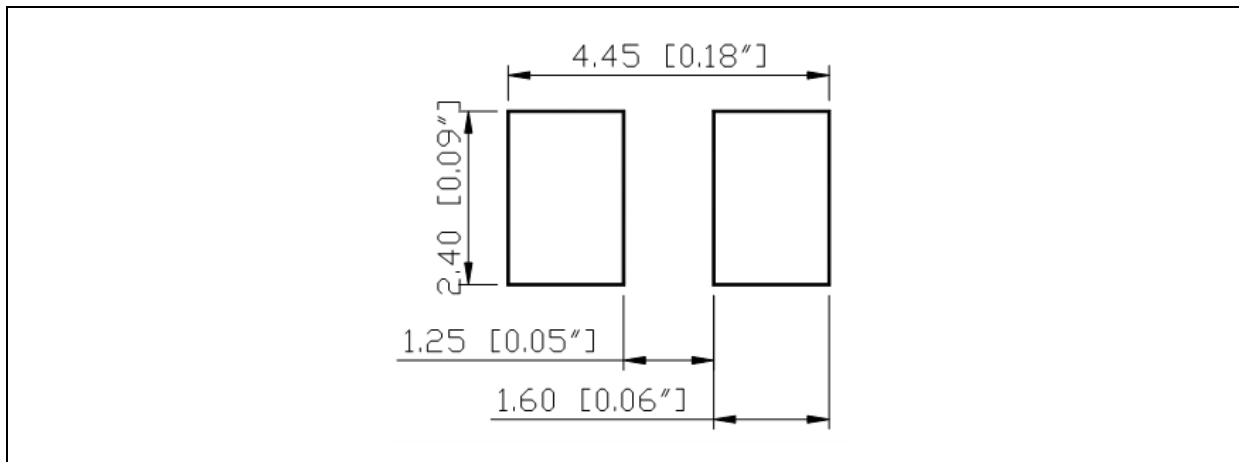
1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2θ_{1/2}) ±5%

OUTLINE DIMENSION:

Package Dimension:



Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
F	2.8	3.1	V
G	3.1	3.4	
H	3.4	3.7	

 Luminous Intensity Classifications ($I_F = 20\text{mA}$):

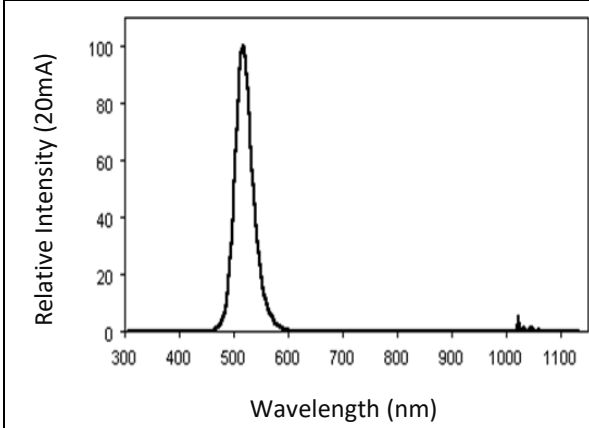
Code	Min.	Max.	Unit
X	2500	3200	mcd
Y	3200	4000	
Z	4000	5200	
A	5200	6800	

 Wavelength Classifications ($I_F = 20\text{mA}$):

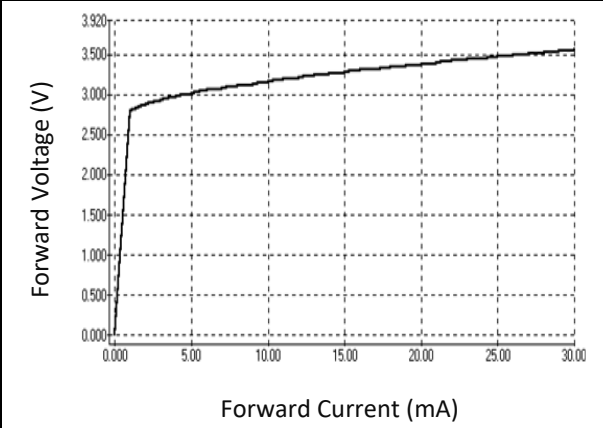
Code	Min.	Max.	Unit
U	520	522.5	nm
V	522.5	525	
W	525	527.5	
X	527.5	530	

ELECTRO-OPTICAL CHARACTERISTICS:

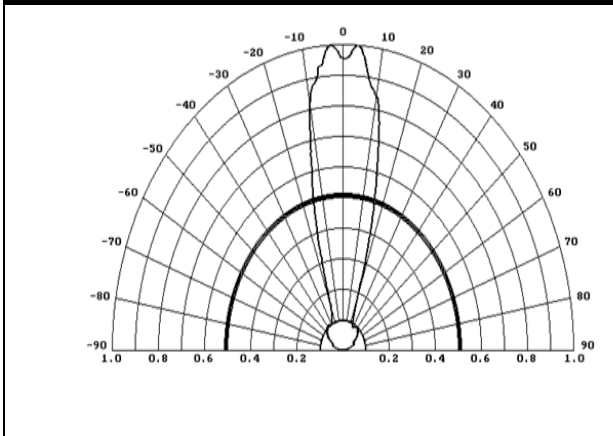
Relative Spectral Distribution



Forward Current v.s. Forward Voltage

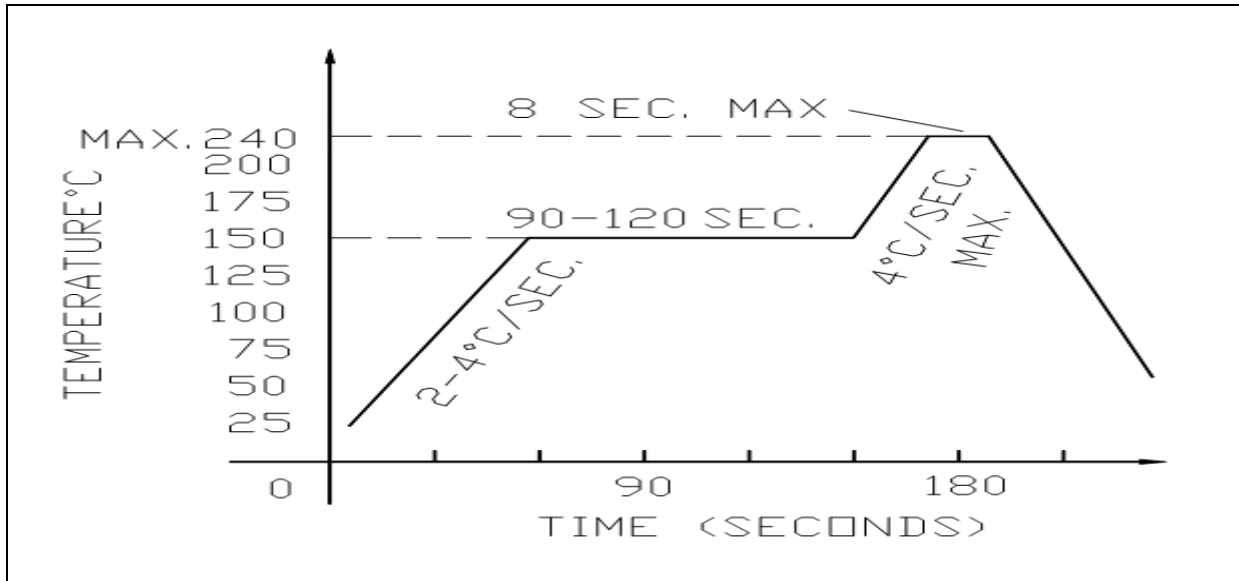


Directive Radiation



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:

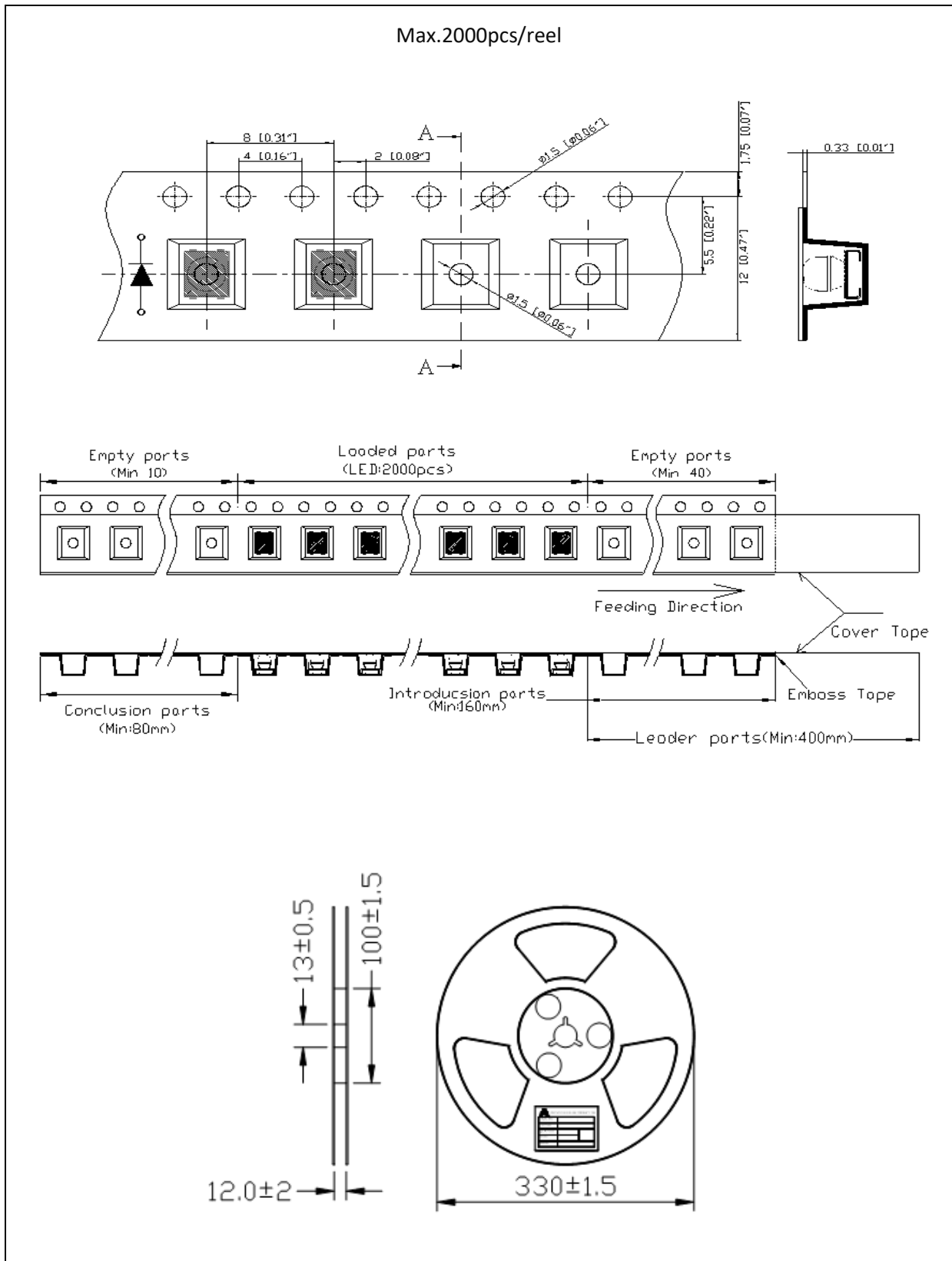


Note:

1. Maximum reflow soldering: 1 time.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

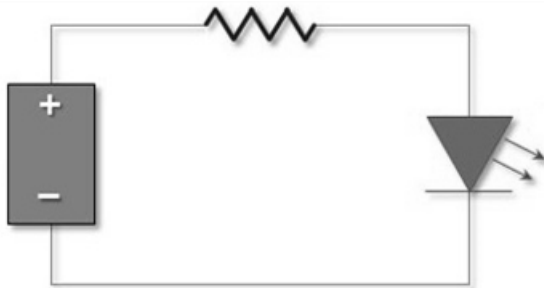
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	20/05/2014	Datasheet set-up.
A1.1	26/08/2020	Revise baking condition.